REMARKS

In view of the above amendment, applicant believes the pending application is in condition for allowance.

Claims 1 and 16 are amended to more fully describe the high-temperature polymer and the soft polymer and highlight the significance of the heat resistance to determination of the present invention. Claim 15 is amended to better define the elements of the power cable construction. New Claim 22 is supported by original Claim 8 and defines the second cable layer as a component in the power cable construction.

Claims 2, 3, and 8 are cancelled. The subject matter of Claim 2 is incorporated into amended Claim 1. The subject matter of Claim 8 is encompassed in new Claim 22.

None of these amendment is new matter.

Claim Rejections – 35 USC § 112, Second Paragraph

The Examiner has rejected Claim 8 of the present application under 35 USC 112, second paragraph, contending that Claim 8 is indefinite because the language of "wherein a semiconductive cable layer" is drawn to the future intended use and functions of the composition. To obviate the rejections, applicants have cancelled Claim 8 and added new Claim 22. Claim 22 is drawn to a power cable construction, specifies a second a cable layer, and specifies that the second cable layer is chemically-crosslinked. Original Claim 8 supports new Claim 22.

Claim Rejections – 35 USC § 102

The present invention is directed to a semiconductive power cable composition that yields a semiconductive cable layer (a) having a heat resistance of less than 100% as measured by a Hot Creep test at a testing temperature of 150 degrees Centigrade and (b) adhering strippably to a second cable layer. Both features are necessary characteristics of the resulting semiconductive cable layer.

The Examiner has rejected Claims 1-9 and 13-16 as being anticipated by European Patent Publication EP 0 334 993 (Watanabe), Claims 1-18 as being anticipated by European Patent Publication EP 0 858 081 (Yoshida), and Claims 1-8, 13-16, and 19-21 as being anticipated by PCT Publication WO 02/31051 (Easter). The applicants respectfully traverse.

The Examiner cites three references against the claims of the present application. While the Examiner presents the references separately, the Examiner essentially uses the references to express a recurring position as demonstrated by the Examiner copying the entire

text of the rejection based on Watanabe from its second sentence into the rejection based on Yoshida, even including "Watanabe" in the Yoshida-based rejection. As such, applicants elect to respond to the references together.

The cited references do not teach heat resistance as a critical feature of the resulting semiconductive cable layer. The Examiner may be correct in that it would be desirable to produce a semiconductive cable layer having the feature; yet the cited references do not express any awareness of the desired feature nor how to achieve the feature. The references are directed to producing strippable cable layers. Any other goal is purely speculative.

Here, the applicants teach that heat resistance of the semiconductive layer is important for use in power cables rated for a conductor operating temperature of 90-degree Centigrade or higher. To that end, applicants specify that heat resistance is defined as "less than 100% as measured by a Hot Creep test at a testing temperature of 150 degrees Centigrade" and that the semiconductive cable layer should achieve that level of heat resistance. The cited references do not teach the selection of a high temperature polymer that would yield the desired heat resistance.

Additionally, the cited references fail to teach how to overcome certain processing characteristics that accompany selection of an appropriate high-temperature polymer. That is, the references do not teach selection of a soft polymer. As defined in the present invention, the soft polymer would enhance the processing characteristics of the high-temperature polymer.

The applicants further teach the degree of processing improvement is bracketed by the required level of processing and the desire to yield a semiconductive layer that strippably adheres to its adjacent layer(s). Based upon the present teaching, the person skilled in the art has the tools to balance the competing interests of processing improvements and strippable adherence. Here, strippably adhere is defined as a "strip tension between 3 and 24 pounds per 0.5 inch wide strip (1.3 to 10.9 kilograms per 13 millimeter wide strip)" and referenced in ANSI/ICEA Standards S-94-649 and S-97-682. Simply put, the application teaches the person skilled in the art how to select an appropriate high-temperature polymer, how to achieve minimum processing needs in view of the high-temperature polymer and equipment parameters and the need for strippably adherence to adjacent layers in the power cable construction. None of the cited references teaches the present invention.

In view of the above-described Amendments and Remarks, the applicants believe the pending application is in condition for allowance.

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Respectfully submitted,

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